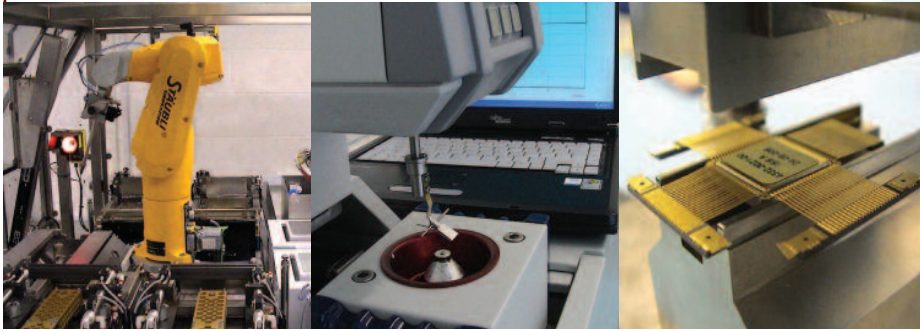


Robotic Terminal Conversion Solder Dipping



microcrossSXT™
SOLDER EXCHANGE TECHNOLOGY



The MicrocrossSXT automated solder-dipping process mitigates tin-whisker formation to increase component reliability.

PB & PB-FREE FINISH

CONFORMANCE WITH GEIA-0006 STANDARD

AUTOMATED DIPPING

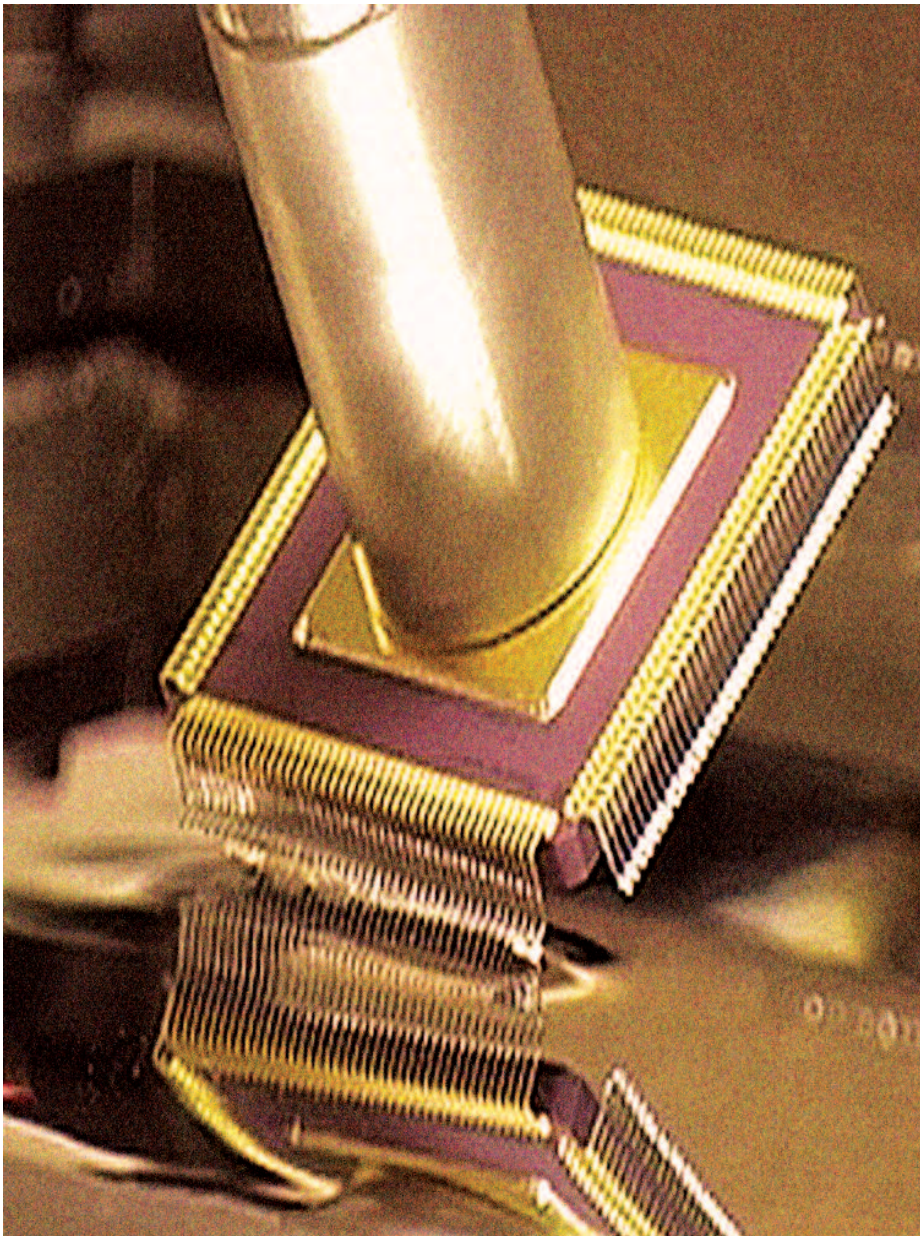
- 6-AXIS ROBOT
- NITROGEN BLANKET
- SOLDER LEVEL SENSING
- TIN & OTHER PLATING REMOVAL

SOLDERABILITY TESTING

J-STD-002

TRIM AND FORM

- FULLY CUSTOMIZABLE
LEAD FORMING
- PTH TO SMT
- FLAT PACK CONVERSION
- QFP & SOIC





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TECHNICAL STRATEGY

Micross policy is to automate technical processes wherever possible. This ensures a high level of consistency and repeatability.

QUALITY

- Quality system is AS9100 Rev. C certified (expires May 7, 2018)
- Full ESD environment (JESD625B compliant)
- Temperature and humidity controls
- Fully traceable documentation
- Integrated production control system

TESTING

- Solderability testing per J-STD-002/MIL-STD-883, Method 2003
- Ionic Cleanliness testing per IPC-TM-650-2.3.25
- XRF testing of solder composition and thickness per MIL-PRF-38535
- Reports available

PACKING

- Tape and reel to EIA 481 standard
- Peel strength test completed on all batches
- Capability to reel all package styles in volume and as component attrition
- Special custom design service available
- Component baking/dry pack to J-STD-033
- Customized labeling available

LEAD ALIGNMENT

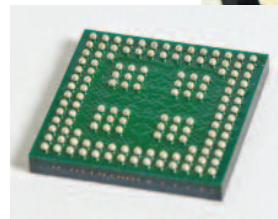
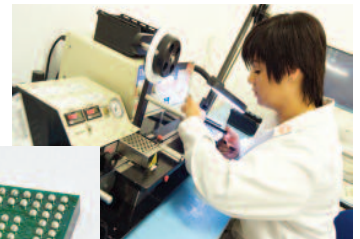
- QFP, SOIC component leads realigned using fully automated computer controlled equipment
- Reworked and packaged to quality standards suitable for machine placement

BGA REBALLING

BGA components reballed using Pb and Pb-free spheres in high volume down to 0.4mm ball pitch and 0.3mm ball diameter.

KEY SERVICES

- BGA Reballing
- Lead Alignment
- Lead Free Terminal Finish conversion to SnPb
- Baking
- Tape and Reeling
- Automated inspection and reporting capabilities
- Lead Trim and Form
- XRF Analysis



For more information visit www.micross.com or contact our sales department at Micross Components
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OUR PRODUCTS & SERVICES DIVISION OFFERS A WEALTH OF EXPERTISE IN DESIGN, PROCESSING AND PRODUCTION OF SEMICONDUCTORS, CONNECTORS AND OTHER ELECTRO-MECHANICAL COMPONENTS WITH THE HIGHEST DEGREE OF QUALITY, HI-RELIABILITY AND PERFORMANCE.



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